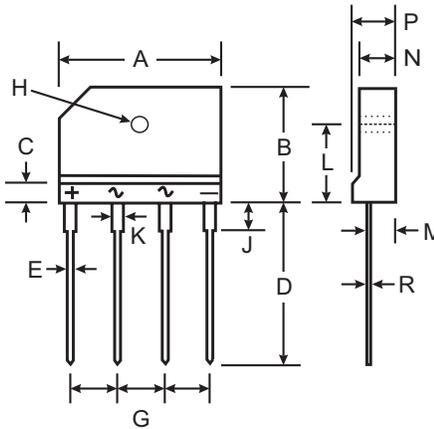


Features

- Glass Passivated Die Construction
- High Case Dielectric Strength of 1500V_{RMS}
- Low Reverse Leakage Current
- Surge Overload Rating to 120A Peak
- Ideal for Printed Circuit Board Applications
- UL Listed Under Recognized Component Index, File Number E94661
- **Lead Free Finish, RoHS Compliant (Note 4)**

Mechanical Data

- Case: KBJ
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish - Tin. Plated Leads, Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: Molded on Body
- Mounting: Through Hole for #6 Screw
- Mounting Torque: 5.0 in-lbs Maximum
- Ordering Information: See Last Page
- Marking: Type Number
- Weight: 4.6 grams (approximate)



KBJ		
Dim	Min	Max
A	24.80	25.20
B	14.70	15.30
C	4.00 Nominal	
D	17.20	17.80
E	0.90	1.10
G	7.30	7.70
H	3.10 \varnothing	3.40 \varnothing
J	3.30	3.70
K	1.50	1.90
L	9.30	9.70
M	2.50	2.90
N	3.40	3.80
P	4.40	4.80
R	0.60	0.80
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	KBJ 4005G	KBJ 401G	KBJ 402G	KBJ 404G	KBJ 406G	KBJ 408G	KBJ 410G	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _C = 115°C	I _O	4.0							A
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave superimposed on rated load	I _{FSM}	120							A
Forward Voltage per element @ I _F = 2.0A	V _{FM}	1.0							V
Peak Reverse Current @ T _C = 25°C at Rated DC Blocking Voltage @ T _C = 125°C	I _{RM}	5.0 500							μA
I ² t Rating for Fusing, t < 8.3ms (Note 3)	I ² t	60							A ² s
Typical Total Capacitance per Element (Note 1)	C _T	40							pF
Typical Thermal Resistance (Note 2)	R _{θJC}	5.5							°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150							°C

- Notes:
1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
 2. Thermal resistance from junction to case per element. Unit mounted on 75 x 75 x 1.6mm aluminum plate heat sink.
 3. Non-repetitive, for t > 1ms and < 8.3ms.
 4. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see *EU Directive Annex Notes 5 and 7*.